

SYSTEM AND METHOD FOR PROVIDING A REDISTRIBUTION
METAL LAYER IN AN INTEGRATED CIRCUIT

ABSTRACT OF THE DISCLOSURE

5 A system and method is disclosed for providing a
redistribution metal layer in an integrated circuit. The
redistribution metal layer is formed from the last metal
layer in the integrated circuit during manufacture of the
integrated circuit before final passivation is applied. The
last metal layer provides sites for solder bump pads used
10 in flip chip interconnection. The redistribution metal
layer can be (1) a flat layer deposited over the next to
last metal layer through an opening in a dielectric layer,
or (2) deposited over an array of vias connected to the
15 next to last metal layer. Space between the solder bump
pads is deposited with narrower traces for connecting
active circuit areas below. A final passivation layer is
deposited to ensure product reliability.